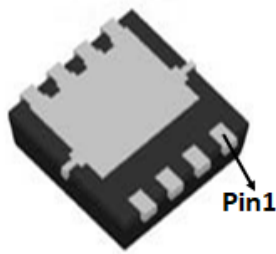
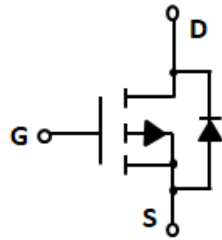
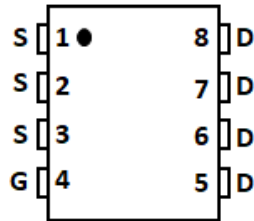


P-Channel Enhancement Mode Field Effect Transistor



DFN3.3X3.3



Product Summary

- V_{DS} -30V
- I_D -40A
- $R_{DS(ON)}$ (at $V_{GS}=-20V$) < 13 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) < 15 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) < 25 mohm

General Description

- Trench Power LV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching

Applications

- Battery management
- Load switch
- Power management

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	-30	V
Gate-source Voltage	V_{GS}	± 25	V
Drain Current	I_D	$T_A=25^\circ C$ @ Steady State	-40
		$T_A=70^\circ C$ @ Steady State	-33
Pulsed Drain Current ^A	I_{DM}	-160	A
Single Pulse Avalanche Energy @ $L=0.5mH$ ^B	E_{AS}	72	mJ
Total Power Dissipation @ $T_A=25^\circ C$ ^C	P_D	32	W
Thermal Resistance Junction-to-Ambient @ Steady State ^D	$R_{\theta JA}$	4.0	$^\circ C/W$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ C$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
LMQ40P03A	F1	Q40P03	5000			13" reel

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =-250μA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V, T _C =25°C			-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±25V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =-250μA	-1.2	-1.8	-2.8	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = -20V, I _D =-20A		8.6	13	mΩ
		V _{GS} = -10V, I _D =-15A		9.8	15	
		V _{GS} = -6.0V, I _D =-12A		12.1	22	
		V _{GS} = -4.5V, I _D =-12A		15.5	25	
Diode Forward Voltage	V _{SD}	I _S =-20A, V _{GS} =0V			-1.2	V
Maximum Body-Diode Continuous Current	I _S				-40	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, f=1MHZ		2050		pF
Output Capacitance	C _{oss}			355		
Reverse Transfer Capacitance	C _{rss}			301		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =-10V, V _{DS} =-15V, I _D =-20A		29.8		nC
Gate Source Charge	Q _{gs}			4.7		
Gate Drain Charge	Q _{gd}			10		
Turn-on Delay Time	t _{D(on)}	V _{GS} =-10V, V _{DD} =-15V, I _D =-1A, R _{GEN} =2.5Ω		14		ns
Turn-on Rise Time	t _r			12		
Turn-off Delay Time	t _{D(off)}			26		
Turn-off Fall Time	t _f			10		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep Initial T_J=25°C.

C. The power dissipation PD is based on T_{J(MAX)}=150°C, using ≤ 10s junction-to-ambient thermal resistance.

D. The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.

■ Typical Performance Characteristics

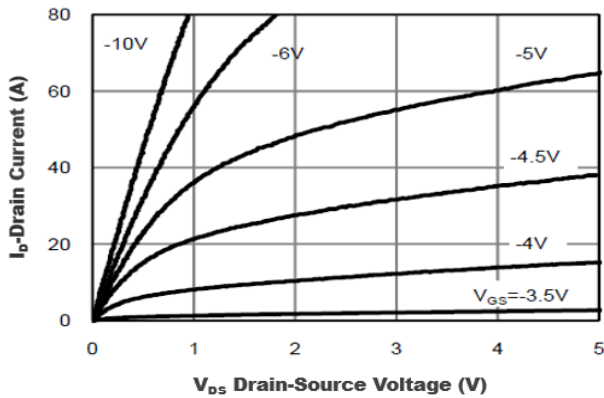


Figure1. Output Characteristics

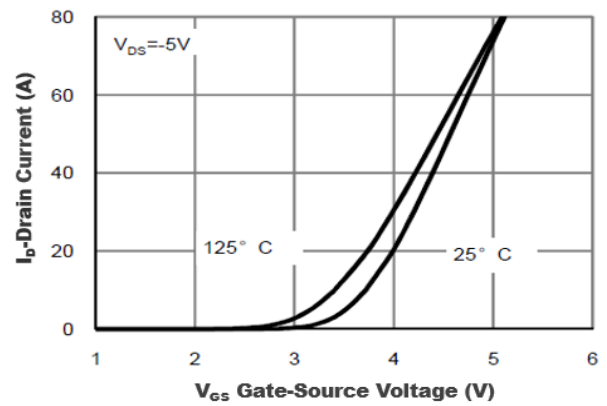


Figure2. Transfer Characteristics

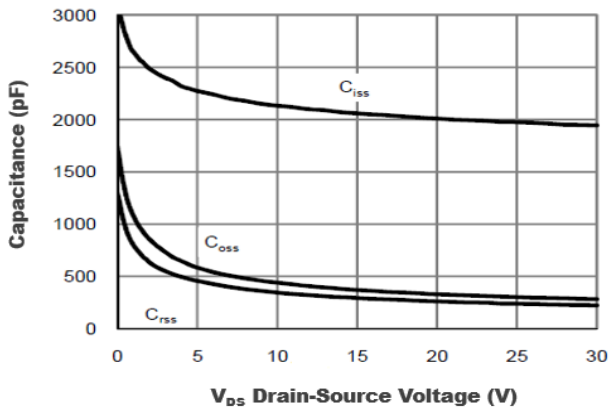


Figure3. Capacitance Characteristics

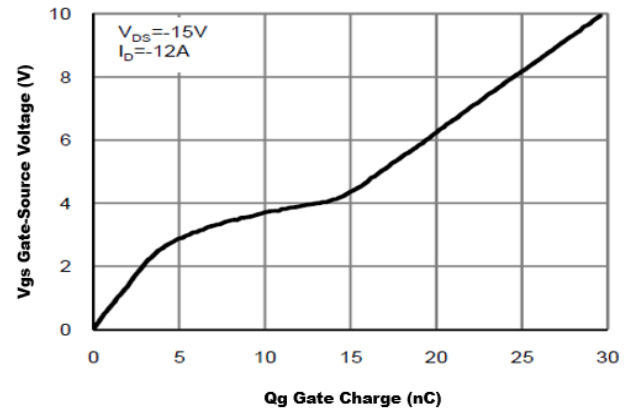


Figure4. Gate Charge

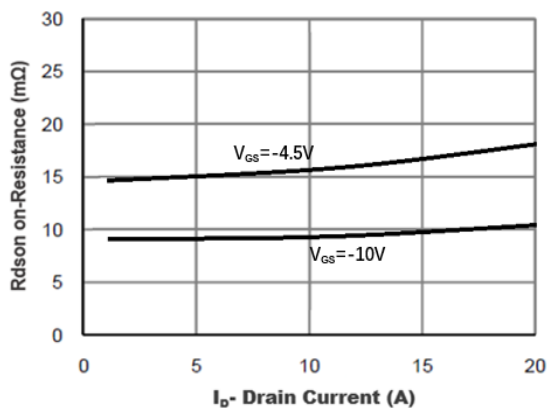


Figure5. Drain-Source on Resistance

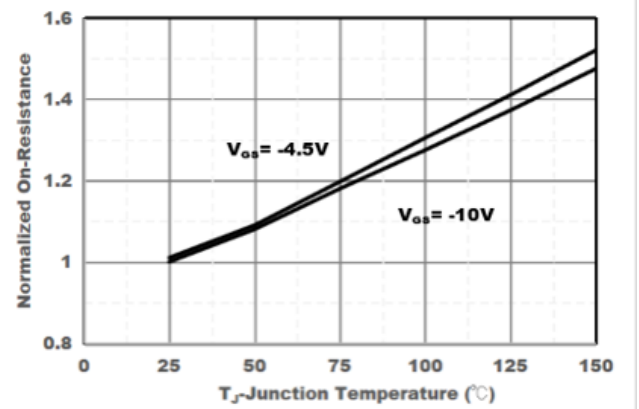


Figure6. Drain-Source on Resistance

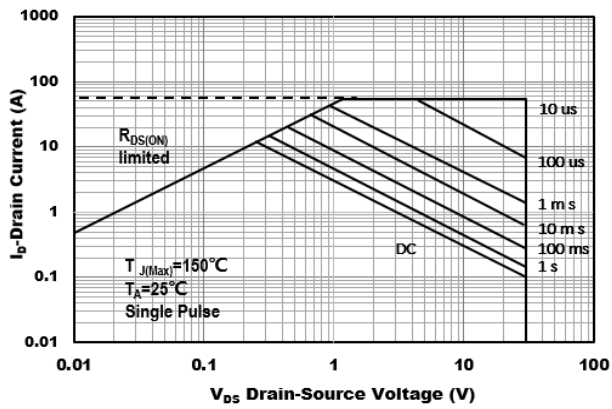


Figure7. Safe Operation Area

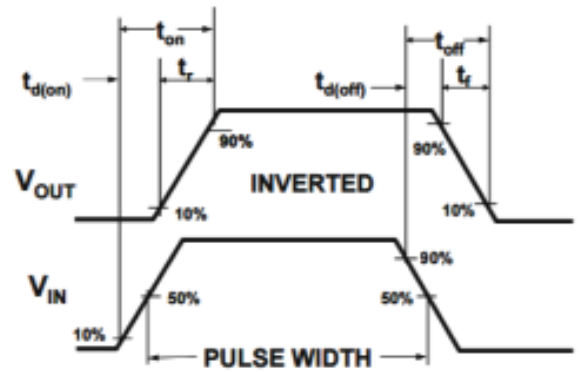
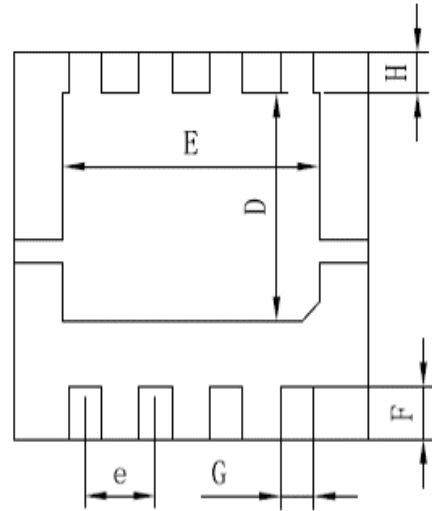
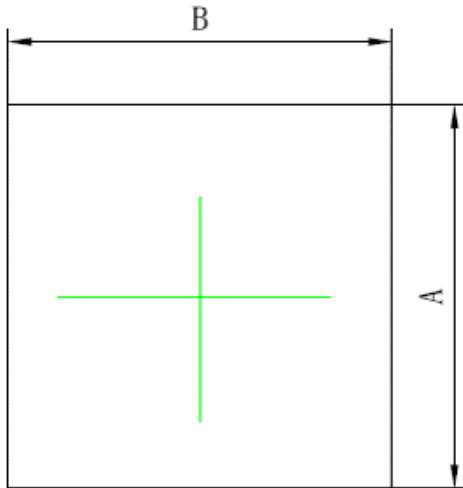


Figure8. Switching wave

■ DFN3.3×3.3 Package information



A	B	C	C1
3.25±0.05	3.25±0.05	0.8±0.05	0.2±0.02
C2	D	E	F
0.05Max	1.9±0.1	2.35±0.15	0.45±0.05
G	H	e	
0.3±0.05	0.35±0.05	0.65±0.05	
单位: mm			

